

## PSF1032468 Datasheet

### SMT JB206, 5th Order, 14.0 GHz Center Frequency and 7.3% Bandwidth Filter

#### General Description

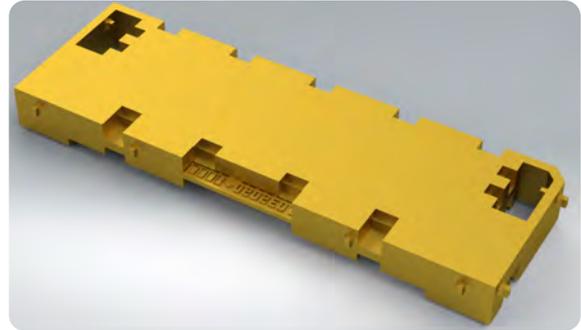
The PSF1032468 is a 5th order interdigital filter, with a pass-band of 13.69–14.53 GHz. It provides <3dB insertion loss with high out of band rejection. The mounting interface provided is a SMT interface compatible with standard attach processes.

#### Applications

- General Purpose BPF

#### Benefits

- Low Loss
- High Rejection
- High Repeatability
- Compact Size
- CTE matched to PCB



Features	
<b>Frequency Range</b>	13.69–14.53 GHz, BPF
<b>Insertion Loss</b>	<3 dB across pass-band
<b>Rejection</b>	>30 dB out-of-band
<b>Package</b>	9.3 x 5.8 x 1.1 mm, bottom-side SMT launches for reflow or epoxy attach

## Performance Specifications

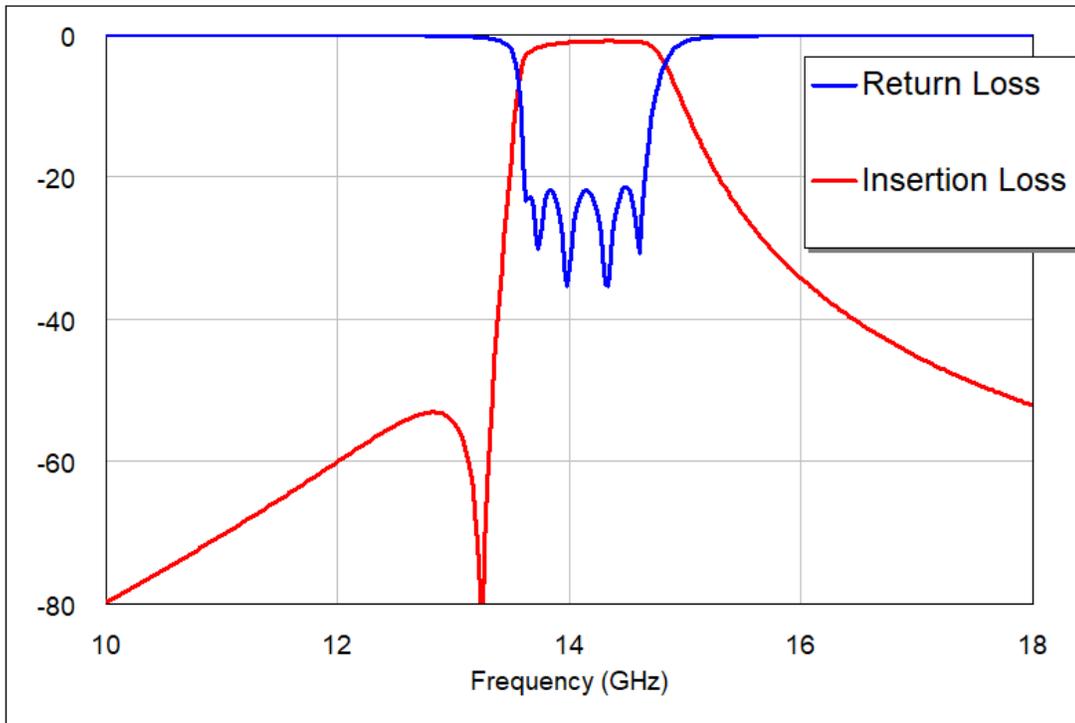
**Table 1: RF Performance**

Parameter	Freq. Range (GHz)	Min.	Typ.	Max.	Unit
Return Loss	13.69–14.53	12	15	-	dB
Insertion Loss	13.69–14.53	-	1.9	3	dB
Lower Rejection	0–13.36	30	50	-	dB
Upper Rejection	15.82–32.0	30	50	-	dB

**Table 2: Absolute Maximum Ratings**

CW Power	5 W
Operating Temp.	-40°C to 85°C
Solder Reflow	260°C max. for 10 seconds, 3 cycles
Epoxy Attach	150°C max. for 90 minutes
Mechanical Vibration	
MIL-STD-883 M2026.4 (Cond. 1F)	20.0 Grms
Mechanical Shock	
MIL-STD-883 M2002.4 (Cond. A)	500 G

## Typical Performance

**Figure 1: RF performance**


*Plots above are preliminary simulation data.*

**PCB Guidelines**
**Figure 2: Recommended PCB Stackup**

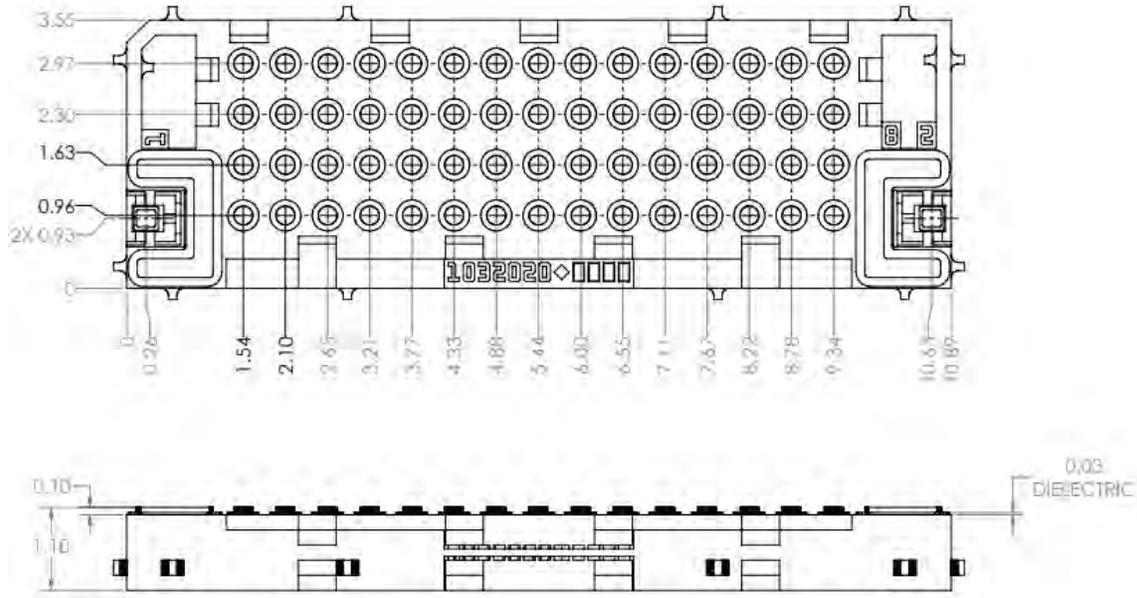
		Layer Stack Legend				
Material	Layer	Thickness	Dielectric Material	Type	Gerber Dk	
	Top Overlay			Legend	GTO	
Surface Material	Top Solder	0.013mm(0.5mil)	SM-003	Solder Mask	GTS 4	
Nickel, Gold	Top Surface Finish	0.004mm(0.2mil)		Surface Finish		
HH	L1- Top Layer	0.035mm(1.4mil)		Signal	GTL	
Core		0.254mm(10.0mil)	RO4350B	Dielectric	3.66	
HH	L2 RF GND	0.018mm(0.7mil)		Signal	G1	
Prepreg		0.381mm(15.0mil)	FR4	Dielectric	4.1	
HH	L3 - Inner 2	0.018mm(0.7mil)		Signal	G2	
Core		0.254mm(10.0mil)	Core-028	Dielectric	4.3	
CF-004	L4 - Bottom Layer	0.035mm(1.4mil)		Signal	GBL	
Nickel, Gold	Bottom Surface Finish	0.004mm(0.2mil)		Surface Finish		
Total thickness: 1.015mm(40.0mil) <u>+/- 10%</u>						

**PCB Design Notes:**

1. Use blind vias (Layer 1 to Layer 2 pair) around RF traces.
2. Use solid ground pour on all ground pins of the part to prevent parasitic inductances.
3. If deviating from the above stackup, the recommended PCB footprint may need to be adjusted for tuning purposes. Please contact Nuvotronics for assistance with tuning.
4. Follow stenciling guidelines outlined in IPC-7525C to prevent over-pasting RF launches (see "PolyStrata SMT Assembly Guide" application note for details).

**Mechanical Information**

**Figure 3: 2D Mechanical Drawing**



*Note: Manufacturing tethers extend past the indicated dimensions of the part. See STEP model for details.*

**Additional Information**

**Table 3: Handling and Ordering Information**

Storage	IAW IPC-4553A
ESD Sensitivity	None
Ordering Information	PSF1032468
Standard Packaging	Gel Pack
Alternative Packaging	Tape & Reel
Component Termination Finish	Immersion Gold

*Note: Detailed handling guidelines can be found in the "General Handling Guidelines" and "PolyStrata SMT Assembly Guide" application notes (see link below).*

- Footprint DXF is available on request.
- Application notes on PCB integration are available at: <https://www.nuvotronics.com/resources/>